

RELIABILITY REPORT
FOR
MAX7410xxA
PLASTIC ENCAPSULATED DEVICES

May 5, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



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Conclusion

The MAX7410 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX7410 5th-order, lowpass, switched-capacitor filters (SCFs) operates from a single +5V supply. This device draws only 1.2mA of supply current and allows corner frequencies from 1Hz to 15kHz, making it ideal for low-power post-DAC filtering and anti-aliasing applications. It features a shutdown mode, which reduces the supply current to 0.2µA.

Two clocking options are available on this device: self-clocking (through the use of an external capacitor) or external clocking for tighter corner-frequency control. An offset adjust pin allows for adjustment of the DC output level.

The MAX7410 Butterworth filter provide a maximally flat passband response. It's fixed response simplifies the design task to selecting a clock frequency.

B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
VDD to GND	-0.3V to +6V
IN, OUT, COM, OS, CLK, SHDN	-0.3V to (VDD + 0.3V)
OUT Short-Circuit Duration	1sec
Operating Temperature Ranges	
MAX7410C_A	0°C to +70°C
MAX7410E_A	-40°C to +85°C
Storage Temperature Range	-65°C to +160°C
Lead Temperature (soldering, 10sec)	+300°C
Continuous Power Dissipation (TA = +70°C)	
8-Pin PDIP	727mW
8-Pin µMAX	330mW
Derates above +70°C	
8-Pin PDIP	9.09mW/°C
8-Pin µMAX	4.10mW/°C

II. Manufacturing Information

A. Description/Function:	5th-Order, Lowpass, Switched-Capacitor Filters
B. Process:	S6 (0.6 micron CMOS)
C. Number of Device Transistors:	1457
D. Fabrication Location:	California, USA
E. Assembly Location:	Malaysia, Thailand or Philippines
F. Date of Initial Production:	July, 1998

III. Packaging Information

A. Package Type:	8 Lead PDIP	8-Lead uMAX
B. Lead Frame:	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-0201-0127	# 05-0201-0128
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1	Level 1

IV. Die Information

A. Dimensions:	59 x 81 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/Si (Aluminum/ Silicon)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.6 microns (as drawn)
F. Minimum Metal Spacing:	0.6 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:

Jim Pedicord (Manager, Rel Operations)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 396 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

└ Thermal acceleration factor assuming a 0.8eV activation energy

$$\lambda = 2.74 \times 10^{-9} \quad \lambda = 2.74 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure the reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on lots exceeding this level. The following Burn-In Schematic (Spec #06-5582) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The AF17-2 die type has been found to have all pins able to withstand a transient pulse of $\pm 2500\text{V}$, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 250\text{mA}$.

Table 1
Reliability Evaluation Test Results

MAX7410xxA

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		396	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	PDIP uMAX	77 77	0 0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

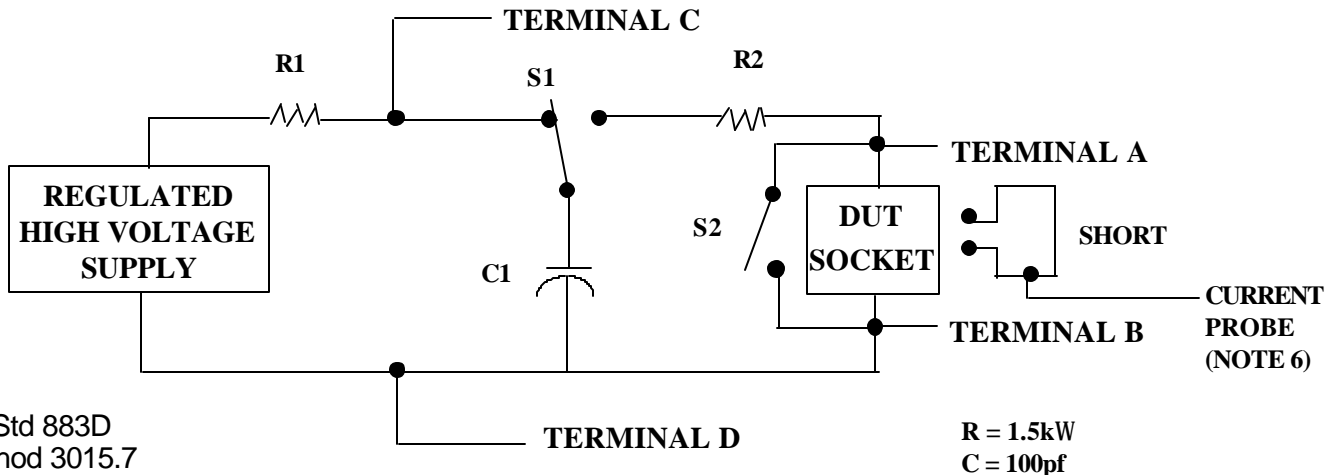
2/ No connects are not to be tested.

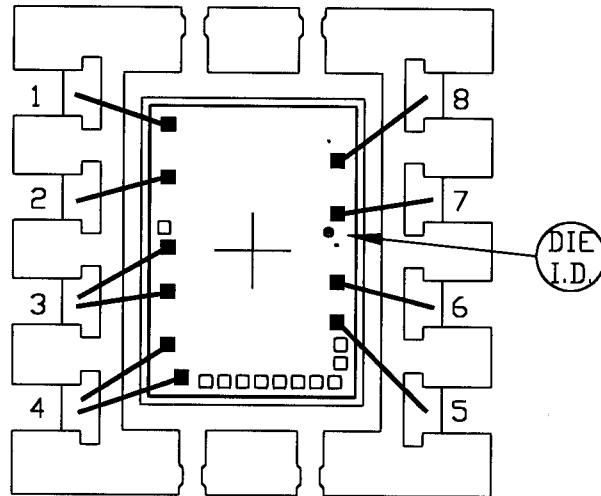
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, $+V_S$, $-V_S$, V_{REF} , etc).

3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





PKG.CODE: U8-1

CAV./PAD SIZE:
68X94

PKG.
DESIGN

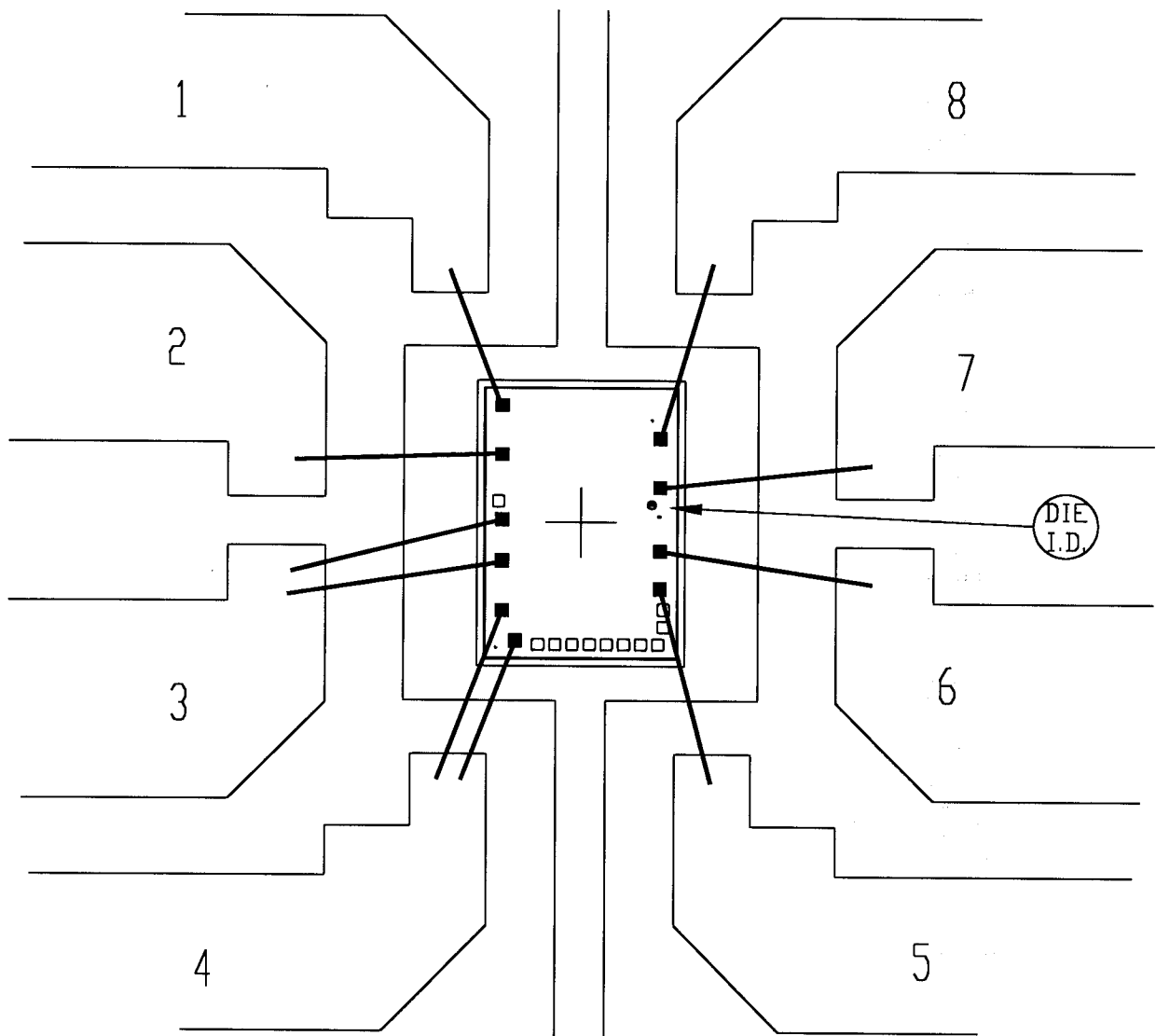
APPROVALS

DATE

MAXIM

BUILDSHEET NUMBER:
05-0201-0128

REV.:
B



PKG.CODE: P8-1

CAV./PAD SIZE:
100 X 100

APPROVALS

DATE

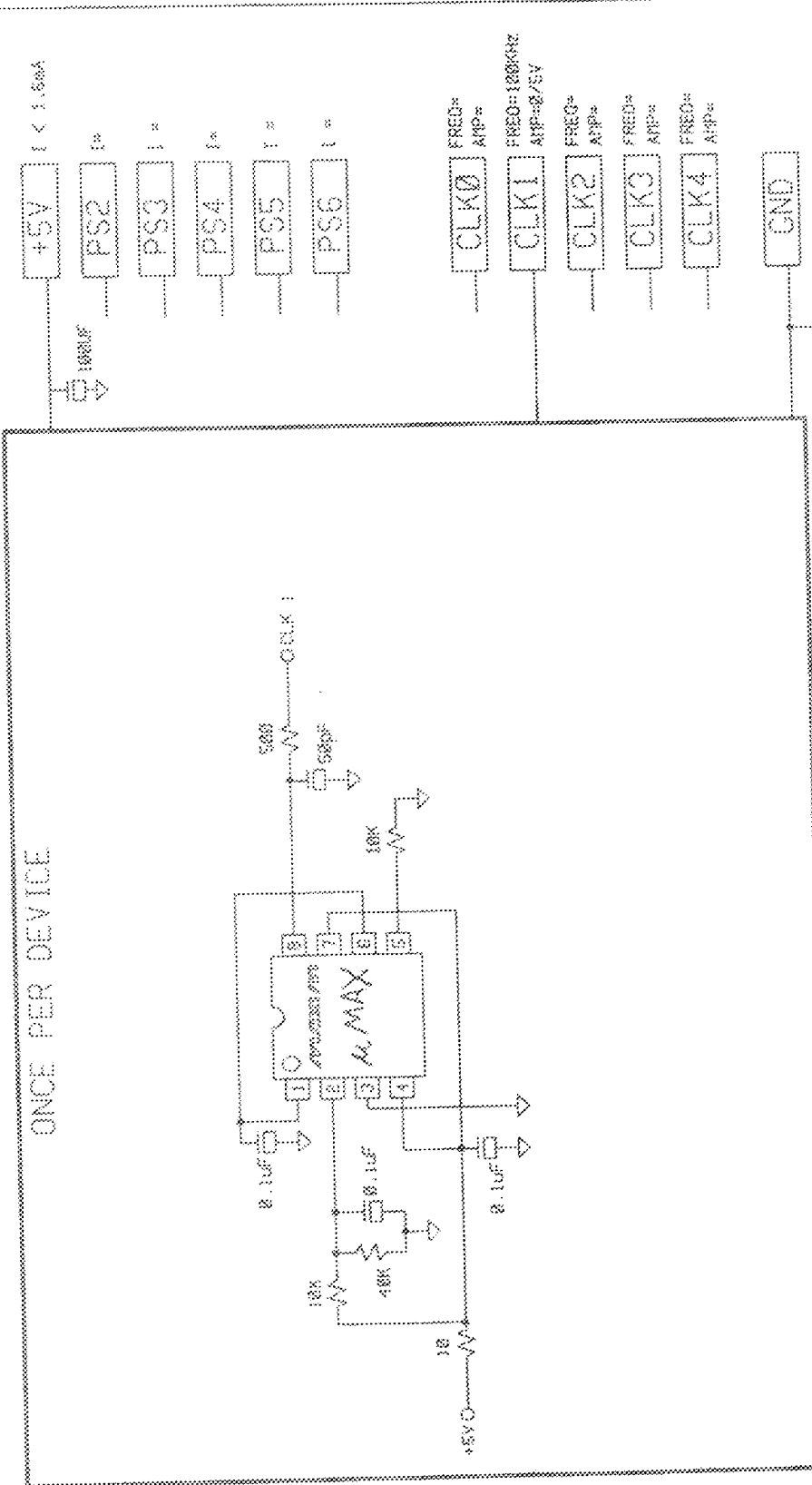
MAXIM

BUILDSHEET NUMBER: 05-0201-0127	REV.: B
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PKG. DESIGN

ONCE PER BOARD

ONCE PER DEVICE



- STEADY STATE LIFE TEST IS PER MIL-STD-883 METHOD 1005.
 - BURN-IN IS PER MIL-STD-883 METHOD 1015. COND. B

MAXIM BURN-IN SCHEMATIC
 DEVICE TYPE(S):
 MAX7480/5/18/11/12/13/14/16
 REFER TO 06-9989 FOR OTHER POSSIBLE DEVICES

SPEC. NO. 06-SS82 REV. A
 DATE: 2/9/00
 DRAWN BY: T. BEJSOVEC

NOTES:
 1. TEMPERATURE: 125C OR EQUIVALENT
 2. TIME: 168 HOURS MIN. OR EQUIVALENT
 3. ALL COMPONENTS AND MATERIAL MUST STAND 150C CONTINUOUS
 4. APPROVED FOR (X) COMMERCIAL (X) MR/880